

REVERSE WIRE BONDING TECHNIQUES

ABSTRACT OF THE DISCLOSURE

5 Thin molded semiconductor device packages that contain two semiconductor dice
and techniques for forming such packages are described. The packages and techniques
mainly involve reverse wirebonding the bonding wires that connect the dice to
surrounding conductive contact leads. Techniques for ball bonding a first end of a
bonding wire to a contact lead and a second end of the bonding wire to a semiconductor
10 die are described. Techniques for stitch bonding a bonding wire to both a contact lead
and a semiconductor die is also described.

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